



#### **60V N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C		
001/	$12m\Omega$ @ $V_{GS} = 10V$	9.8A		
60V	$14m\Omega @ V_{GS} = 4.5V$	8.4A		

#### **Features and Benefits**

- 100% Unclamped Inductive Switch (UIS) Test in Production
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Ensures On-State Losses Are Minimized
- Excellent Q<sub>GD</sub> x R<sub>DS(ON)</sub> Product (FOM)
- Advanced Technology for DC-DC Converters
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Description and Applications**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

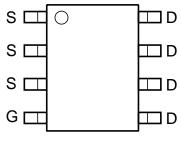
- Power Management Functions
- DC-DC Converters
- Backlighting

#### **Mechanical Data**

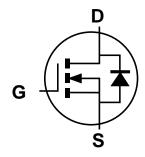
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)







Top View Internal Schematic



Equivalent Circuit

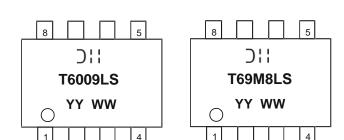
#### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMT69M8LSS-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



);;= Manufacturer's Marking T6009LS & T69M8LS = Date Code Marking YY or \( \overline{YY} = \text{Year (ex: 17 = 2017)} \) WW = Week (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	60	V		
Gate-Source Voltage	V <sub>GSS</sub>	±16	V		
Continuous Dusis Comment (Nata C) V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	9.8 7.9	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	12.2 9.5	А
Maximum Continuous Body Diode Forward Curre	I <sub>S</sub>	3	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle =	I <sub>DM</sub>	60	Α		
Avalanche Current, L = 0.1mH	I <sub>AS</sub>	25	А		
Avalanche Energy, L = 0.1mH	E <sub>AS</sub>	31.5	mJ		

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		$P_{D}$	1.25	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>θJA</sub>	100	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s		55.5	°C/W
Total Power Dissipation (Note 6)		$P_{D}$	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	ם	75	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	42	°C/W
Thermal Resistance, Junction to Case (Note 6)		R <sub>0</sub> JC	12	°C/W
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to +150	°C

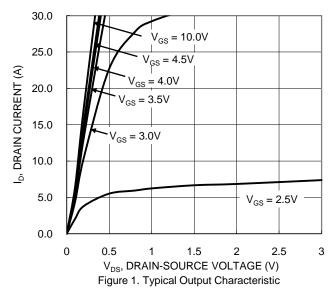
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

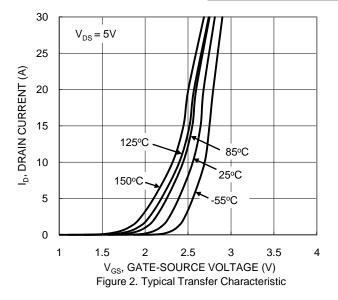
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 48V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.7	_	2	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	_	_	9.8	12	mΩ	$V_{GS} = 10V, I_D = 13.5A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	12	14		$V_{GS} = 4.5V, I_D = 11.5A$	
Diode Forward Voltage	V <sub>SD</sub>	_	0.9	1.2	V	$V_{GS} = 0V, I_S = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	_	1,925	_		$V_{DS} = 30V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Output Capacitance	Coss	_	438	_	pF		
Reverse Transfer Capacitance	Crss	_	41	_			
Gate Resistance	$R_{G}$	_	1.7	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_G$	_	33.5	_			
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_{G}$	_	15.6	_	nC	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Gate-Source Charge	Q <sub>GS</sub>	_	4.7	_	nc	$V_{DS} = 30V, I_D = 13.5A$	
Gate-Drain Charge	$Q_{GD}$	_	5.3	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.5	_		$V_{DD} = 30V, V_{GS} = 10V,$ $R_G = 6\Omega, I_D = 13.5A$	
Turn-On Rise Time	t <sub>R</sub>	_	8.6	_			
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	35.9	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	15.7	_			
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	18.2	_	ns	1 42.54 4:/44 4004/	
Body Diode Reverse Recovery Charge	$Q_{RR}$	_	33.1	_	nC	$I_F = 13.5A$ , di/dt = 400A/ $\mu$ s	

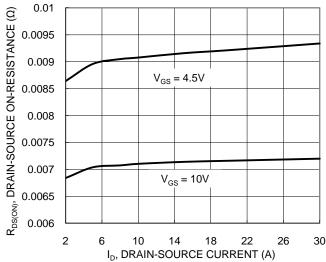
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:











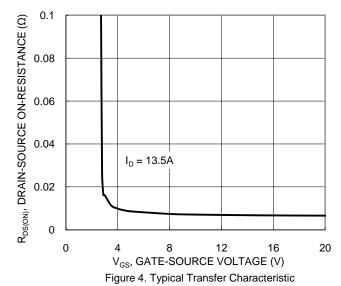
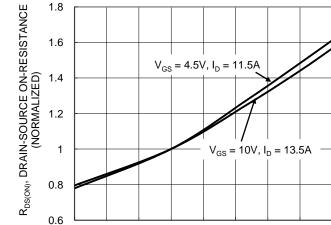
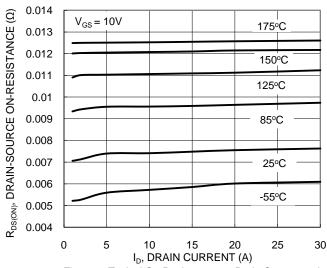


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage



25



 $T_J$ , JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Junction Temperature

50

75

100

Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

-50





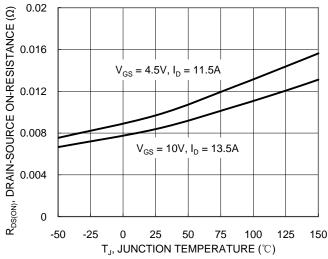


Figure 7. On-Resistance Variation with Junction Temperature

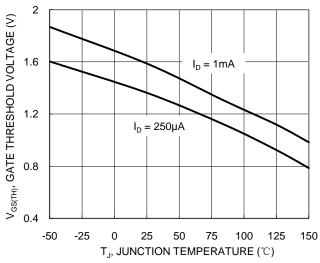


Figure 8. Gate Threshold Variation vs. Junction Temperature

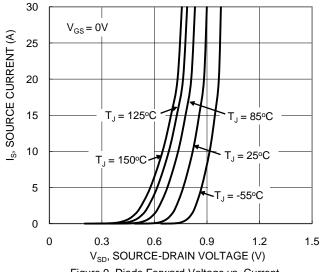


Figure 9. Diode Forward Voltage vs. Current

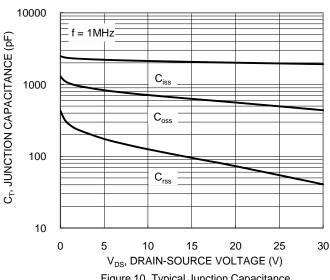
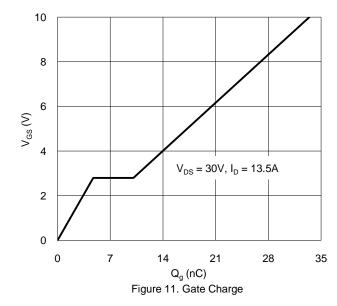
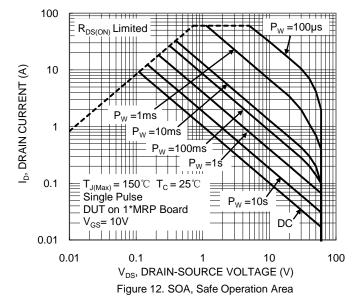


Figure 10. Typical Junction Capacitance







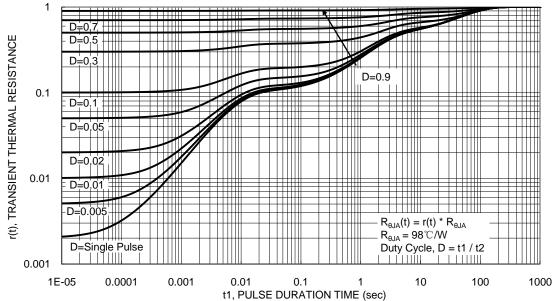


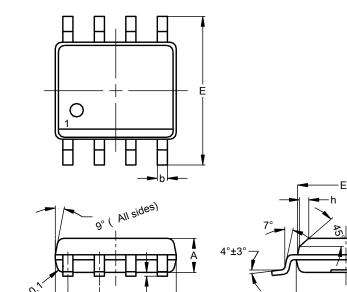
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

**SO-8** 



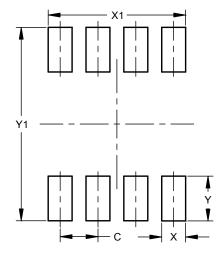
SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
<b>A</b> 1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е	-	-	1.27			
h	ı	-	0.35			
L	0.62	0.82	0.72			
Q	0.60	0.70	0.65			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8

-Gauge Plane Seating Plane



Dimensions	Value (in mm)				
С	1.27				
Х	0.802				
X1	4.612				
Y	1.505				
Y1	6.50				



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